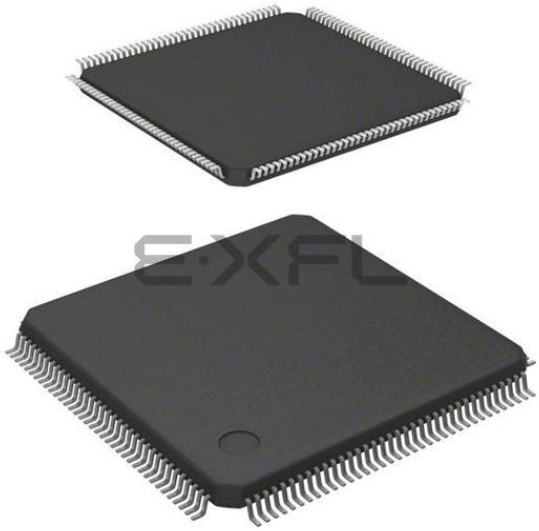

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	DMA, I²S, POR, PWM, WDT
Number of I/O	115
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	80K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 40x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32f303zdt6

1 Introduction

This datasheet provides the ordering information and mechanical device characteristics of the STM32F303xD/E microcontrollers.

This STM32F303xD/E datasheet should be read in conjunction with the reference manual of STM32F303xB/C/D/E, STM32F358xC and STM32F328x4/6/8 devices (RM0316) available on STMicroelectronics website at *www.st.com*.

For information on the ARM® Cortex®-M4 core with FPU, refer to the following documents:

- *Cortex® -M4 with FPU Technical Reference Manual*, available from the www.arm.com website
- *STM32F3 and STM32F4 Series Cortex® -M4 programming manual* (PM0214) available on STMicroelectronics website at *www.st.com*.

Table 5. Timer feature comparison

Timer type	Timer	Counter resolution	Counter type	Prescaler factor	DMA request generation	Capture/ compare channels	Complementary outputs
Advanced	TIM1, TIM8, TIM20	16-bit	Up, Down, Up/Down	Any integer between 1 and 65536	Yes	4	Yes
General-purpose	TIM2	32-bit	Up, Down, Up/Down	Any integer between 1 and 65536	Yes	4	No
General-purpose	TIM3, TIM4	16-bit	Up, Down, Up/Down	Any integer between 1 and 65536	Yes	4	No
General-purpose	TIM15	16-bit	Up	Any integer between 1 and 65536	Yes	2	1
General-purpose	TIM16, TIM17	16-bit	Up	Any integer between 1 and 65536	Yes	1	1
Basic	TIM6, TIM7	16-bit	Up	Any integer between 1 and 65536	Yes	0	No

Note: TIM1/8/20/2/3/4/15/16/17 can have PLL as clock source, and therefore can be clocked at 144 MHz.

3.18.1 Advanced timers (TIM1, TIM8, TIM20)

The advanced-control timers (TIM1, TIM8, TIM20) can each be seen as a three-phase PWM multiplexed on six channels. They have complementary PWM outputs with programmable inserted dead-times. They can also be seen as complete general-purpose timers. The four independent channels can be used for:

- Input capture
- Output compare
- PWM generation (edge or center-aligned modes) with full modulation capability (0-100%)
- One-pulse mode output

In debug mode, the advanced-control timer counter can be frozen and the PWM outputs disabled to turn off any power switches driven by these outputs.

Many features are shared with those of the general-purpose TIM timers (described in *Section 3.18.2*) using the same architecture, so the advanced-control timers can work together with the TIM timers via the Timer Link feature for synchronization or event chaining.

3.18.2 General-purpose timers (TIM2, TIM3, TIM4, TIM15, TIM16, TIM17)

There are up to six synchronizable general-purpose timers embedded in the STM32F303xD/E (see *Table 5* for differences). Each general-purpose timer can be used to generate PWM outputs, or act as a simple time base.

4 Pinout and pin description

Figure 4. STM32F303xD/E LQFP64 pinout

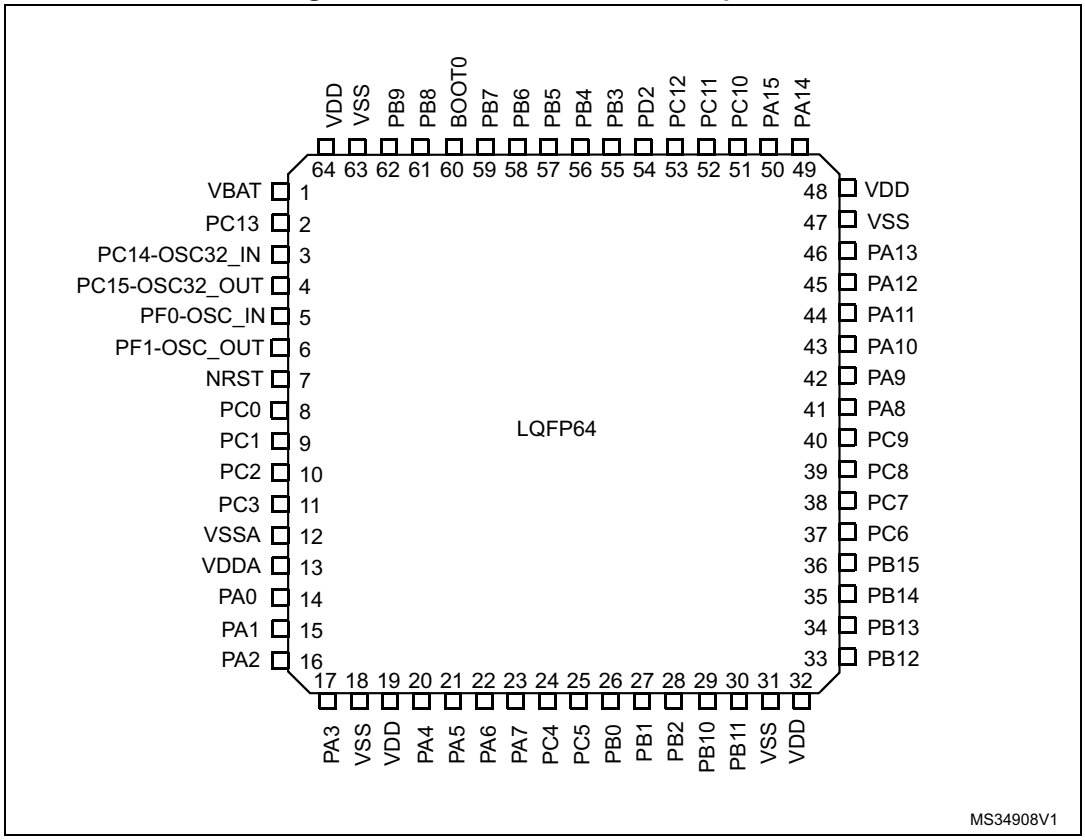
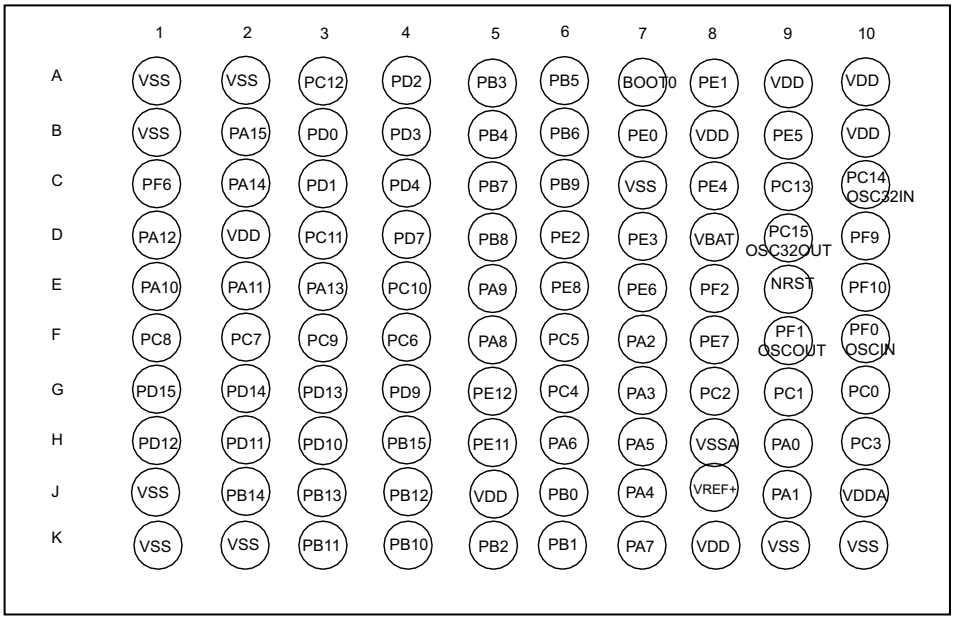


Figure 7. STM32F303xD/E WLCSP100 ballout



MSv40453V1

Table 13. STM32F303xD/E pin definitions (continued)

Pin number					Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP64	LQFP100	UFBGA100	WLCSP100	LQFP144						
-	45	M11	-	67	PE14	I/O	TTa	(1)	EVENTOUT, TIM1_CH4, SPI4_MOSI, TIM1_BKIN2, FMC_D11	ADC4_IN1(3)
-	46	M12	-	68	PE15	I/O	TTa	(1)	EVENTOUT, TIM1_BKIN, USART3_RX, FMC_D12	ADC4_IN2(3)
29	47	L10	K4	69	PB10	I/O	TTa	-	TIM2_CH3, TSC_SYNC, USART3_TX, EVENTOUT	COMP5_INM, OPAMP3_VINM, OPAMP4_VINM
30	48	L11	K3	70	PB11	I/O	TTa	-	TIM2_CH4, TSC_G6_IO1, USART3_RX, EVENTOUT	ADC12_IN14, COMP6_INP, OPAMP4_VINP
31	49	F12	K1, J1, K2	71	VSS	S	-	-	-	-
32	50	G12	J5	72	VDD	S	-	-	-	-
33	51	L12	J4	73	PB12	I/O	TTa	(5)	TSC_G6_IO2, I2C2_SMBAL, SPI2_NSS/I2S2_WS, TIM1_BKIN, USART3_CK, EVENTOUT	ADC4_IN3(3), COMP3_INM, OPAMP4_VOUT
34	52	K12	J3	74	PB13	I/O	TTa	-	TSC_G6_IO3, SPI2_SCK/I2S2_CK, TIM1_CH1N, USART3_CTS, EVENTOUT	ADC3_IN5(3), COMP5_INP, OPAMP3_VINP, OPAMP4_VINP
35	53	K11	J2	75	PB14	I/O	TTa	-	TIM15_CH1, TSC_G6_IO4, SPI2_MISO/I2S2ext_SD, TIM1_CH2N, USART3_RTS, EVENTOUT	ADC4_IN4(3), COMP3_INP, OPAMP2_VINP
36	54	K10	H4	76	PB15	I/O	TTa	-	RTC_REFIN, TIM15_CH2, TIM15_CH1N, TIM1_CH3N, SPI2_MOSI/I2S2_SD, EVENTOUT	ADC4_IN5(3), COMP6_INM
-	55	K9	-	77	PD8	I/O	TTa	(1)	EVENTOUT, USART3_TX, FMC_D13	ADC4_IN12, OPAMP4_VINM

Table 13. STM32F303xD/E pin definitions (continued)

Pin number					Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP64	LQFP100	UFBGA100	WLCSP100	LQFP144						
37	63	E12	F4	96	PC6	I/O	FT	-	EVENTOUT, TIM3_CH1, TIM8_CH1, I2S2_MCK, COMP6_OUT	-
38	64	E11	F2	97	PC7	I/O	FT	-	EVENTOUT, TIM3_CH2, TIM8_CH2, I2S3_MCK, COMP5_OUT	-
39	65	E10	F1	98	PC8	I/O	FT	-	EVENTOUT, TIM3_CH3, TIM8_CH3, COMP3_OUT	-
40	66	D12	F3	99	PC9	I/O	FTf	-	EVENTOUT, TIM3_CH4, I2C3_SDA, TIM8_CH4, I2SCKIN, TIM8_BKIN2	-
41	67	D11	F5	100	PA8	I/O	FTf	-	MCO, I2C3_SCL, I2C2_SMBAL, I2S2_MCK, TIM1_CH1, USART1_CK, COMP3_OUT, TIM4_ETR, EVENTOUT	-
42	68	D10	E5	101	PA9	I/O	FTf	-	I2C3_SMBAL, TSC_G4_IO1, I2C2_SCL, I2S3_MCK, TIM1_CH2, USART1_TX, COMP5_OUT, TIM15_BKIN, TIM2_CH3, EVENTOUT	-
43	69	C12	E1	102	PA10	I/O	FTf	-	TIM17_BKIN, TSC_G4_IO2, I2C2_SDA, SPI2_MISO/I2S2ext_SD, TIM1_CH3, USART1_RX, COMP6_OUT, TIM2_CH4, TIM8_BKIN, EVENTOUT	-
44	70	B12	E2	103	PA11	I/O	FT	-	SPI2_MOSI/I2S2_SD, TIM1_CH1N, USART1_CTS, COMP1_OUT, CAN_RX, TIM4_CH1, TIM1_CH4, TIM1_BKIN2, EVENTOUT	USB_DM

Table 13. STM32F303xD/E pin definitions (continued)

Pin number					Pin name (function after reset)	Pin type	I/O structure	Notes	Alternate functions	Additional functions
LQFP64	LQFP100	UFBGA100	WLCSP100	LQFP144						
45	71	A12	D1	104	PA12	I/O	FT	-	TIM16_CH1, I2SCKIN, TIM1_CH2N, USART1_RTS, COMP2_OUT, CAN_TX, TIM4_CH2, TIM1_ETR, EVENTOUT	USB_DP
46	72	A11	E3	105	PA13	I/O	FT	-	SWDIO-JTMS, TIM16_CH1N, TSC_G4_IO3, IR-OUT, USART3_CTS, TIM4_CH3, EVENTOUT	-
-	-	-	-	106	PH2	I/O	FT	(1)	EVENTOUT	-
47	74	F11	A1, A2, B1	107	VSS	S	-	-	-	-
48	75	G11	D2	108	VDD	S	-	-	-	-
49	76	A10	C2	109	PA14	I/O	FTf	-	SWCLK-JTCK, TSC_G4_IO4, I2C1_SDA, TIM8_CH2, TIM1_BKIN, USART2_TX, EVENTOUT	-
50	77	A9	B2	110	PA15	I/O	FTf	-	JTDI, TIM2_CH1/TIM2_ETR, TIM8_CH1, TSC_SYNC, I2C1_SCL, SPI1_NSS, SPI3_NSS/I2S3_WS, USART2_RX, TIM1_BKIN, EVENTOUT	-
51	78	B11	E4	111	PC10	I/O	FT	-	EVENTOUT, TIM8_CH1N, UART4_TX, SPI3_SCK/I2S3_CK, USART3_TX	-
52	79	C10	D3	112	PC11	I/O	FT	-	EVENTOUT, TIM8_CH2N, UART4_RX, SPI3_MISO/I2S3ext_SD, USART3_RX	-

Table 14. STM32F303xD/E alternate function mapping (continued)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS_AF	TIM2/15/16/17/EVENT	I2C3/TIM1/2/3/4/8/20/15/GPCOMP1	I2C3/TIM8/20/15/GPCOMP7/TSC	I2C1/2/TIM1/8/16/17	SPI1/SPI2/I2S2/SPI3/I2S3/SPI4/UART4/5/TIM8/Infrared	SPI2/I2S2/SPI3/I2S3/TIM1/8/20/Infrared	USART1/2/3/CAN/GPCOMP3/5/6	I2C3/GPCOMP1/2/3/4/5/6	CAN/TIM1/8/15	TIM2/3/4/8/17	TIM1/8	FSMC/TIM1	-	-	EVENT
Port D	PD5	-	EVENT OUT	-	-	-	-	-	USART2_TX	-	-	-	-	FMC_NWE	-	-	-
	PD6	-	EVENT OUT	TIM2_CH4	-	-	-	-	USART2_RX	-	-	-	-	FMC_NWAIT	-	-	-
	PD7	-	EVENT OUT	TIM2_CH3	-	-	-	-	USART2_CK	-	-	-	-	FMC_NE1/FMC_NCE2	-	-	-
	PD8	-	EVENT OUT	-	-	-	-	-	USART3_TX	-	-	-	-	FMC_D13	-	-	-
	PD9	-	EVENT OUT	-	-	-	-	-	USART3_RX	-	-	-	-	FMC_D14	-	-	-
	PD10	-	EVENT OUT	-	-	-	-	-	USART3_CK	-	-	-	-	FMC_D15	-	-	-
	PD11	-	EVENT OUT	-	-	-	-	-	USART3_CTS	-	-	-	-	FMC_A16	-	-	-
	PD12	-	EVENT OUT	TIM4_CH1	TSC_G8_IO1	-	-	-	USART3_RTS	-	-	-	-	FMC_A17	-	-	-
	PD13	-	EVENT OUT	TIM4_CH2	TSC_G8_IO2	-	-	-	-	-	-	-	-	FMC_A18	-	-	-
	PD14	-	EVENT OUT	TIM4_CH3	TSC_G8_IO3	-	-	-	-	-	-	-	-	FMC_D0	-	-	-
	PD15	-	EVENT OUT	TIM4_CH4	TSC_G8_IO4	-	-	SPI2_NSS	-	-	-	-	-	FMC_D1	-	-	-

Table 14. STM32F303xD/E alternate function mapping (continued)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS_AF	TIM2/15/16/17/EVENT	I2C3/TIM12/3/4/8/20/15/GPCOMP1	I2C3/TIM8/20/15/GPCOMP7/TSC	I2C1/2/TIM1/8/16/17	SPI1/SPI2/I2S2/SPI3/I2S3/SPI4/UART4/5/TIM8/Infrared	SPI2/I2S2/SPI3/I2S3/TIM1/8/20/Infrared	USART1/2/3/CAN/GPCOMP3/5/6	I2C3/GPCOMP1/2/3/4/5/6	CAN/TIM1/8/15	TIM2/3/4/8/17	TIM1/8	FSMC/TIM1	-	-	EVENT
Port F	PF8	-	EVENT OUT	TIM20_BKIN2	-	-	-	-	-	-	-	-	-	FMC_NIOWR	-	-	-
	PF9	-	EVENT OUT	TIM20_BKIN	TIM15_CH1	-	SPI2_SCK	-	-	-	-	-	-	FMC_CD	-	-	-
	PF10	-	EVENT OUT	TIM20_BKIN2	TIM15_CH2	-	SPI2_SCK	-	-	-	-	-	-	FMC_INTR	-	-	-
	PF11	-	EVENT OUT	TIM20_ETR	-	-	-	-	-	-	-	-	-	-	-	-	-
	PF12	-	EVENT OUT	TIM20_CH1	-	-	-	-	-	-	-	-	-	FMC_A6	-	-	-
	PF13	-	EVENT OUT	TIM20_CH2	-	-	-	-	-	-	-	-	-	FMC_A7	-	-	-
	PF14	-	EVENT OUT	TIM20_CH3	-	-	-	-	-	-	-	-	-	FMC_A8	-	-	-
	PF15	-	EVENT OUT	TIM20_CH4	-	-	-	-	-	-	-	-	-	FMC_A9	-	-	-
Port G	PG0	-	EVENT OUT	TIM20_CH1N	-	-	-	-	-	-	-	-	-	FMC_A10	-	-	-
	PG1	-	EVENT OUT	TIM20_CH2N	-	-	-	-	-	-	-	-	-	FMC_A11	-	-	-
	PG2	-	EVENT OUT	TIM20_CH3N	-	-	-	-	-	-	-	-	-	FMC_A12	-	-	-
	PG3	-	EVENT OUT	TIM20_BKIN	-	-	-	-	-	-	-	-	-	FMC_A13	-	-	-
	PG4	-	EVENT OUT	TIM20_BKIN2	-	-	-	-	-	-	-	-	-	FMC_A14	-	-	-

Table 14. STM32F303xD/E alternate function mapping (continued)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
		SYS_AF	TIM2/15/16/17/EVENT	I2C3/TIM1/2/3/4/8/20/15/GPCOMP1	I2C3/TIM8/20/15/GPCOMP7/TSC	I2C1/2/TIM1/8/16/17	SPI1/SPI2/I2S2/SPI3/I2S3/SPI4/UART4/5/TIM8/Infrared	SPI2/I2S2/SPI3/I2S3/TIM1/8/20/Infrared	USART1/2/3/CAN/GPCOMP3/5/6	I2C3/GPCOMP1/2/3/4/5/6	CAN/TIM1/8/15	TIM2/3/4/8/17	TIM1/8	FSMC/TIM1	-	-	EVENT
Port H	PH0	-	EVENT OUT	TIM20_CH1	-	-	-	-	-	-	-	-	-	FMC_A0	-	-	-
	PH1	-	EVENT OUT	TIM20_CH2	-	-	-	-	-	-	-	-	-	FMC_A1	-	-	-
	PH2	-	EVENT OUT	-	-	-	-	-	-	-	-	-	-	-	-	-	-

Table 15. Memory map, peripheral register boundary addresses (continued)

Bus	Boundary address	Size (bytes)	Peripheral
-	0x4001 8000 - 0x4001 FFFF	32 K	Reserved
	0x4001 5400 - 0x4001 7FFF	11 K	Reserved
	0x4001 5000 - 0x4001 53FF	1 K	TIM20
	0x4001 4C00 - 0x4001 4FFF	1 K	Reserved
	0x4001 4800 - 0x4001 4BFF	1 K	TIM17
	0x4001 4400 - 0x4001 47FF	1 K	TIM16
	0x4001 4000 - 0x4001 43FF	1 K	TIM15
	0x4001 3C00 - 0x4001 3FFF	1 K	SPI4
	0x4001 3800 - 0x4001 3BFF	1 K	USART1
	0x4001 3400 - 0x4001 37FF	1 K	TIM8
	0x4001 3000 - 0x4001 33FF	1 K	SPI1
APB2	0x4001 2C00 - 0x4001 2FFF	1 K	TIM1
	0x4001 0800 - 0x4001 2BFF	9 K	Reserved
	0x4001 0400 - 0x4001 07FF	1 K	EXTI
	0x4001 0000 - 0x4001 03FF	1 K	SYSCFG + COMP + OPAMP
-	0x4000 7C00 - 0x4000 FFFF	32 K	Reserved

6.3 Operating conditions

6.3.1 General operating conditions

Table 19. General operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
f_{HCLK}	Internal AHB clock frequency	-	0	72	MHz
f_{PCLK1}	Internal APB1 clock frequency	-	0	36	
f_{PCLK2}	Internal APB2 clock frequency	-	0	72	
V_{DD}	Standard operating voltage	-	2	3.6	V
V_{DDA}	Analog operating voltage (OPAMP and DAC not used)	Must have a potential equal to or higher than V_{DD}	2	3.6	V
	Analog operating voltage (OPAMP and DAC used)		2.4	3.6	
V_{BAT}	Backup operating voltage	-	1.65	3.6	V
V_{IN}	I/O input voltage	TC I/O	-0.3	V_{DD}+0.3	V
		TTa I/O	-0.3	V_{DDA}+0.3	
		FT and FTf I/O(1)	-0.3	5.5	
		BOOT0	0	5.5	
P_D	Power dissipation at T_A = 85 °C for suffix 6 or T_A = 105 °C for suffix 7(2)	LQFP144	-	606	mW
		WLCSP100	-	454	
		LQFP100	-	476	
		UFBGA100	-	339	
		LQFP64	-	435	
T_A	Ambient temperature for 6 suffix version	Maximum power dissipation	-40	85	°C
		Low power dissipation(3)	-40	105	
	Ambient temperature for 7 suffix version	Maximum power dissipation	-40	105	°C
		Low power dissipation(3)	-40	125	
T_J	Junction temperature range	6 suffix version	-40	105	°C
		7 suffix version	-40	125	

1. To sustain a voltage higher than V_{DD}+0.3 V, the internal pull-up/pull-down resistors must be disabled.
2. If T_A is lower, higher P_D values are allowed as long as T_J does not exceed T_{Jmax} (see *Section 7.7: Thermal characteristics*).
3. In low power dissipation state, T_A can be extended to this range as long as T_J does not exceed T_{Jmax} (see *Section 7.7: Thermal characteristics*).

Table 26. Typical and maximum current consumption from the V_{DDA} supply (continued)

Symbol	Parameter	Conditions (1)	f_{HCLK}	V_{DDA} = 2.4 V				V_{DDA} = 3.6 V				Unit
				Typ	Max @ T_A(2)			Typ	Max @ T_A(2)			
					25 °C	85 °C	105 °C		25 °C	85 °C	105 °C	
I_{DDA}	Supply current in Run mode, code executing from Flash or RAM	HSE bypass	1 MHz	1.9	3.1	3.6	4.4	2.5	3.7	4.4	5.5	µA
		HSI clock	64 MHz	266	290	301	306	295	320	335	341	
			48 MHz	216	237	247	251	240	262	274	279	
			32 MHz	170	188	196	199	190	208	217	221	
			24 MHz	148	164	170	172	166	182	189	192	
			8 MHz	70	78	81	82	84	92	95	97	

1. Current consumption from the V_{DDA} supply is independent of whether the peripherals are on or off. Furthermore when the PLL is off, I_{DDA} is independent from the frequency.
2. Data based on characterization results, not tested in production.

Table 27. Typical and maximum V_{DD} consumption in Stop and Standby modes

Symbol	Parameter	Conditions	Typ @V_{DD} (V_{DD}=V_{DDA})						Max			Unit
			2.0 V	2.4 V	2.7 V	3.0 V	3.3 V	3.6 V	T_A = 25 °C	T_A = 85 °C	T_A = 105 °C	
I_{DD}	Supply current in Stop mode	Regulator in run mode, all oscillators OFF	18.4	18.7	18.8	18.9	19.0	19.1	47	435	940	µA
		Regulator in low-power mode, all oscillators OFF	6.80	6.94	7.11	7.18	7.26	7.39	33	408	898	
	Supply current in Standby mode	LSI ON and IWDG ON	0.72	0.87	0.99	1.10	1.23	1.37	-	-	-	
		LSI OFF and IWDG OFF	0.57	0.68	0.76	0.85	0.94	1.03	6.2	8.6	13.5	

Table 45. Asynchronous non-multiplexed SRAM/PSRAM/NOR read timings(1)

Symbol	Parameter	Min	Max	Unit
$t_{w(NE)}$	FMC_NE low time	2THCLK– 1	2THCLK+1	ns
$t_{v(NOE\_NE)}$	FMC_NEx low to FMC_NOE low	0	1	
$t_{w(NOE)}$	FMC_NOE low time	2THCLK	2THCLK+ 1.5	
$t_{h(NE\_NOE)}$	FMC_NOE high to FMC_NE high hold time	0.5	-	
$t_{v(A\_NE)}$	FMC_NEx low to FMC_A valid	-	3	
$t_{h(A\_NOE)}$	Address hold time after FMC_NOE high	0	-	
$t_{v(BL\_NE)}$	FMC_NEx low to FMC_BL valid	-	2 (NA)	
$t_{h(BL\_NOE)}$	FMC_BL hold time after FMC_NOE high	0	-	
$t_{su(Data\_NE)}$	Data to FMC_NEx high setup time	THCLK + 6	-	
$t_{su(Data\_NOE)}$	Data to FMC_NOEx high setup time	THCLK +7	-	
$t_{h(Data\_NOE)}$	Data hold time after FMC_NOE high	0	-	
$t_{h(Data\_NE)}$	Data hold time after FMC_NEx high	0	-	
$t_{v(NADV\_NE)}$	FMC_NEx low to FMC_NADV low	-	2	
$t_{w(NADV)}$	FMC_NADV low time	-	THCLK +1.5	

1. Based on characterization, not tested in production

Table 46. Asynchronous non-multiplexed SRAM/PSRAM/NOR read-NWAIT timings(1)

Symbol	Parameter	Min	Max	Unit
$t_{w(NE)}$	FMC_NE low time	7THCLK +0.5	7THCLK+ 1	ns
$t_{w(NOE)}$	FMC_NWE low time	6THCLK -1.5	6THCLK +2	
$t_{su(NWAIT\_NE)}$	FMC_NWAIT valid before FMC_NEx high	4THCLK +5	-	
$t_{h(NE\_NWAIT)}$	FMC_NEx hold time after FMC_NWAIT invalid	4THCLK-3	-	

1. Based on characterization, not tested in production.

Figure 22. Asynchronous multiplexed PSRAM/NOR read timings

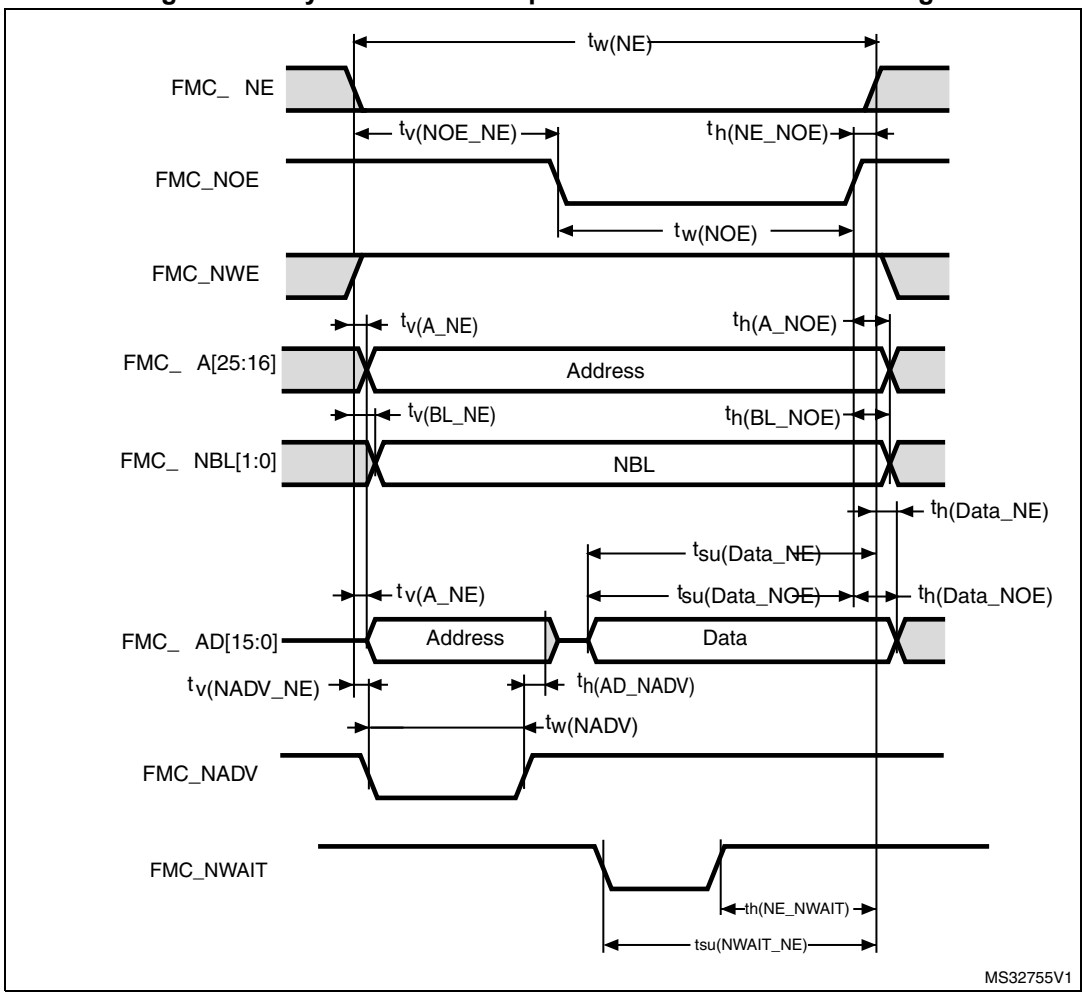


Table 50. Asynchronous multiplexed PSRAM/NOR read timings(1)

Symbol	Parameter	Min	Max	Unit
$t_{w(NE)}$	FMC_NE low time	3THCLK-0.5	3THCLK+1	ns
$t_{v(NOE\_NE)}$	FMC_NEx low to FMC_NOE low	2THCLK	2THCLK+1	
$t_{w(NOE)}$	FMC_NOE low time	THCLK-2	THCLK+2	
$t_{h(NE\_NOE)}$	FMC_NOE high to FMC_NE high hold time	0	-	
$t_{v(A\_NE)}$	FMC_NEx low to FMC_A valid	-	1.5	
$t_{v(NADV\_NE)}$	FMC_NEx low to FMC_NADV low	0	2	
$t_{w(NADV)}$	FMC_NADV low time	THCLK-2	THCLK+2	
$t_{h(AD\_NADV)}$	FMC_AD(address) valid hold time after FMC_NADV high	0	-	
$t_{h(A\_NOE)}$	Address hold time after FMC_NOE high	THCLK-0.5	-	
$t_{h(BL\_NOE)}$	FMC_BL time after FMC_NOE high	0	-	

Input/output AC characteristics

The definition and values of input/output AC characteristics are given in *Figure 40* and *Table 68*, respectively.

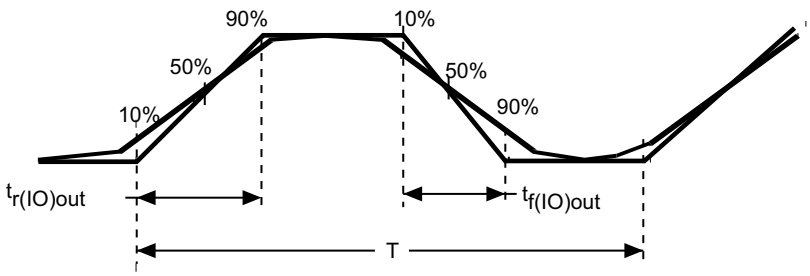
Unless otherwise specified, the parameters given are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 19*.

Table 68. I/O AC characteristics(1)

OSPEEDRy [1:0] value(1)	Symbol	Parameter	Conditions	Min	Max	Unit
x0	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	2(3)	MHz
	$t_{f(IO)out}$	Output high to low level fall time	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	125(3)	ns
	$t_{r(IO)out}$	Output low to high level rise time		-	125(3)	
01	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	10(3)	MHz
	$t_{f(IO)out}$	Output high to low level fall time	C_L = 50 pF, V_{DD} = 2 V to 3.6 V	-	25(3)	ns
	$t_{r(IO)out}$	Output low to high level rise time		-	25(3)	
11	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 30 pF, V_{DD} = 2.7 V to 3.6 V	-	50(3)	MHz
			C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	30(3)	
			C_L = 50 pF, V_{DD} = 2 V to 2.7 V	-	20(3)	
	$t_{f(IO)out}$	Output high to low level fall time	C_L = 30 pF, V_{DD} = 2.7 V to 3.6 V	-	5(3)	ns
			C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	8(3)	
			C_L = 50 pF, V_{DD} = 2 V to 2.7 V	-	12(3)	
	$t_{r(IO)out}$	Output low to high level rise time	C_L = 30 pF, V_{DD} = 2.7 V to 3.6 V	-	5(3)	
			C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	8(3)	
			C_L = 50 pF, V_{DD} = 2 V to 2.7 V	-	12(3)	
FM+ configuration(4)	$f_{max(IO)out}$	Maximum frequency(2)	C_L = 50 pF, V_{DD} = 2 to 3.6 V	-	2(4)	MHz
	$t_{f(IO)out}$	Output high to low level fall time		-	12(4)	ns
	$t_{r(IO)out}$	Output low to high level rise time		-	34(4)	
-	t_{EXTIpw}	Pulse width of external signals detected by the EXTI controller	-	10(3)	-	ns

1. The I/O speed is configured using the OSPEEDRx[1:0] bits. Refer to the RM0316 reference manual for a description of GPIO Port configuration register.
2. The maximum frequency is defined in *Figure 40*.
3. Guaranteed by design, not tested in production.
4. The I/O speed configuration is bypassed in FM+ I/O mode. Refer to the reference manual RM0316 for a description of FM+ I/O mode configuration.

Figure 40. I/O AC characteristics definition



Maximum frequency is achieved if $(t_r + t_f) \le 2/3)T$ and if the duty cycle is (45-55%) when loaded by C_L (1)

MS36445V1

1. See *Table 68: I/O AC characteristics*.

6.3.16 NRST pin characteristics

The NRST pin input driver uses CMOS technology. It is connected to a permanent pull-up resistor, R_{PU} (see *Table 66*).

Unless otherwise specified, the parameters given in *Table 69* are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 19*.

Table 69. NRST pin characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IL(NRST)}$ (1)	NRST Input low level voltage	-	-	-	$0.3V_{DD}+0.07$ (1)	V
$V_{IH(NRST)}$ (1)	NRST Input high level voltage	-	$0.445V_{DD}+0.398$ (1)	-	-	
$V_{hys(NRST)}$	NRST Schmitt trigger voltage hysteresis	-	-	200	-	mV
R_{PU}	Weak pull-up equivalent resistor (2)	$V_{IN} = V_{SS}$	25	40	55	kΩ
$V_{F(NRST)}$ (1)	NRST Input filtered pulse	-	-	-	100 (1)	ns
$V_{NF(NRST)}$ (1)	NRST Input not filtered pulse	-	500 (1)	-	-	ns

1. Guaranteed by design, not tested in production.
2. The pull-up is designed with a true resistance in series with a switchable PMOS. This PMOS contribution to the series resistance must be minimum (~10% order).

Table 83. ADC accuracy - limited test conditions, 64-pin packages(1)(2) (continued)

Symbol	Parameter	Conditions			Min (3)	Typ	Max (3)	Unit
SNR(4)	Signal-to-noise ratio	ADC clock freq. ≤ 72 MHz Sampling freq ≤ 5 Msps V_{DDA} = 3.3 V 25°C 64-pin package	Single ended	Fast channel 5.1 Ms	66	67	-	dB
				Slow channel 4.8 Ms	66	67	-	
			Differential	Fast channel 5.1 Ms	69	70	-	
				Slow channel 4.8 Ms	69	70	-	
THD(4)	Total harmonic distortion		Single ended	Fast channel 5.1 Ms	-	-80	-80	
				Slow channel 4.8 Ms	-	-78	-77	
			Differential	Fast channel 5.1 Ms	-	-83	-82	
				Slow channel 4.8 Ms	-	-81	-80	

1. ADC DC accuracy values are measured after internal calibration.
2. ADC accuracy vs. negative Injection Current: Injecting negative current on any analog input pins should be avoided as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative current.
Any positive injection current within the limits specified for $I_{INJ(PIN)}$ and $\Sigma I_{INJ(PIN)}$ in *Section 6.3.15* does not affect the ADC accuracy.
3. Data based on characterization results, not tested in production.
4. Value measured with a -0.5 dB full scale 50 kHz sine wave input signal.

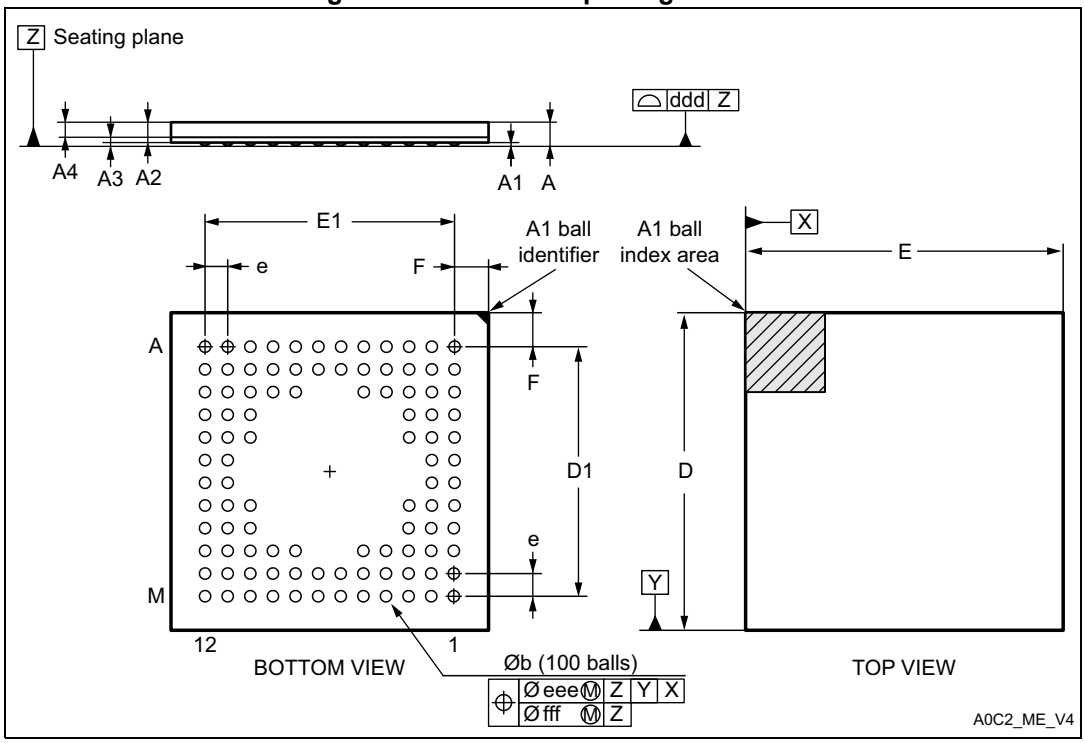
Table 84. ADC accuracy, 64-pin packages(1)(2)(3)

Symbol	Parameter	Conditions			Min(4)	Max (4)	Unit
ET	Total unadjusted error	ADC clock freq. ≤ 72 MHz, Sampling freq. ≤ 5 Msps 2.0 V ≤ V_{DDA} ≤ 3.6 V 64-pin package	Single ended	Fast channel 5.1 Ms	-	±6.5	LSB
				Slow channel 4.8 Ms	-	±6.5	
			Differential	Fast channel 5.1 Ms	-	±4	
				Slow channel 4.8 Ms	-	±4.5	
EO	Offset error		Single ended	Fast channel 5.1 Ms	-	±3	
				Slow channel 4.8 Ms	-	±3	
			Differential	Fast channel 5.1 Ms	-	±2.5	
				Slow channel 4.8 Ms	-	±2.5	
EG	Gain error		Single ended	Fast channel 5.1 Ms	-	±6	
				Slow channel 4.8 Ms	-	±6	
			Differential	Fast channel 5.1 Ms	-	±3.5	
				Slow channel 4.8 Ms	-	±4	
ED	Differential linearity error		Single ended	Fast channel 5.1 Ms	-	±1.5	
				Slow channel 4.8 Ms	-	±1.5	
			Differential	Fast channel 5.1 Ms	-	±1.5	
				Slow channel 4.8 Ms	-	±1.5	

7.3 UFBGA100 package information

UFBGA100 is a 100-ball, 7 x 7 mm, 0.50 mm pitch, ultra fine pitch ball grid array package.

Figure 57. UFBGA100 package outline



1. Drawing is not to scale.

Table 93. UFBGA100 package mechanical data

Symbol	millimeters			inches[1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.460	0.530	0.600	0.0181	0.0209	0.0236
A1	0.050	0.080	0.110	0.0020	0.0031	0.0043
A2	0.400	0.450	0.500	0.0157	0.0177	0.0197
A3	-	0.130	-	-	0.0051	-
A4	0.270	0.320	0.370	0.0106	0.0126	0.0146
b	0.200	0.250	0.300	0.0079	0.0098	0.0118
D	6.950	7.000	7.050	0.2736	0.2756	0.2776
D1	5.450	5.500	5.550	0.2146	0.2165	0.2185
E	6.950	7.000	7.050	0.2736	0.2756	0.2776
E1	5.450	5.500	5.550	0.2146	0.2165	0.2185
e	-	0.500	-	-	0.0197	-
F	0.700	0.750	0.800	0.0276	0.0295	0.0315

Table 97. WLCSP100 recommended PCB design rules (0.4 mm pitch)

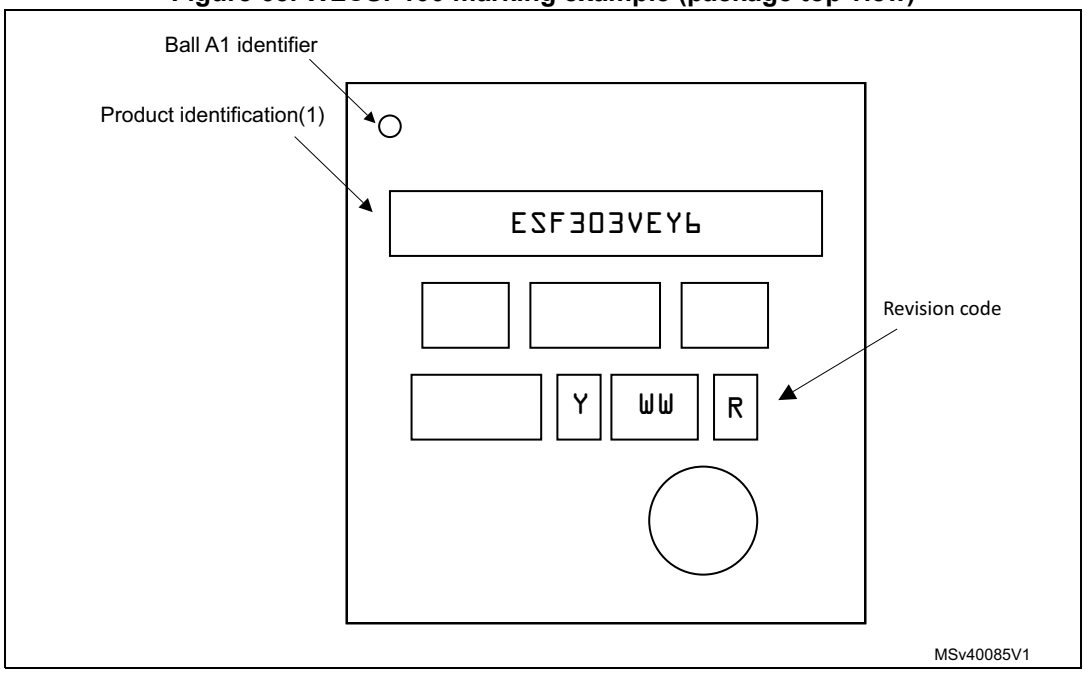
Dimension	Recommended values
Pitch	0.4 mm
Dpad	0.225 mm
Dsm	0.290 mm
Stencil thickness	0.1 mm

Device marking for WLCSP100

The following figure gives an example of topside marking orientation versus pin 1 identifier location.

Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

Figure 65. WLCSP100 marking example (package top view)



1. Parts marked as “ES”, “E” or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.